

# FH18P06G

## -60V P-Channel MOSFET

### Description

The FH18P06G uses advanced SGT technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. The package form is PDFN5x6-8L which accords with the RoHS standard and Halogen Free standard.

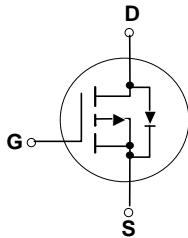
### General Features

- ◆  $V_{DSS} = -60V$ ,  $I_D = -80A$
- ◆  $R_{DS(ON)} = 8.5 m\Omega$  (Typ) @  $V_{GS} = -10V$   
 $R_{DS(ON)} = 10.5 m\Omega$  (Typ) @  $V_{GS} = -4.5V$
- ◆ Fast Switching
- ◆ Low Gate Charge and  $R_{DS(on)}$
- ◆ Low Reverse transfer capacitances

### Applications

- ◆ Battery switching application
- ◆ Hard switched and high frequency circuits
- ◆ Power management

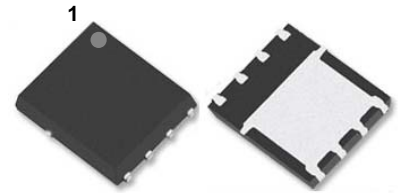
### P-Channel MOSFET



Schematic diagram



Marking and pin assignment



PDFN5x6-8L top and bottom view

### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise specified )

| Symbol         | Parameter  |                     | Value           | Units      |
|----------------|--|---------------------|-----------------|------------|
| $V_{DSS}$      | Drain - to - Source Voltage                      |                     | -60             | V          |
| $I_D$          | Continuous Drain Current                         | $T_C = 25^\circ C$  | -80             | A          |
|                | Continuous Drain Current                         | $T_C = 100^\circ C$ | -50             | A          |
| $I_{DM}^{a1}$  | Pulsed Drain Current                             |                     | -320            | A          |
| $V_{GS}$       | Gate - to - Source Voltage                       |                     | $\pm 20$        | V          |
| $P_D$          | Power Dissipation                                |                     | 35              | W          |
| $E_{AS}^{a2}$  | Single pulse avalanche energy                    |                     | 450             | mJ         |
| $T_J, T_{stg}$ | Operating Junction and Storage Temperature Range |                     | 150, -55 to 150 | $^\circ C$ |
| $T_L$          | Maximum Temperature for Soldering                |                     | 300             | $^\circ C$ |

### Thermal Characteristics

| Symbol          | Parameter                                   | Value | Units        |
|-----------------|---|-------|--------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction - to - Case    | 2.8   | $^\circ C/W$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction - to - Ambient | 60    | $^\circ C/W$ |

## Electrical Characteristics (T<sub>j</sub>= 25 °C unless otherwise specified )

| Static Characteristics |                                   |  |       |      |      |       |
|------------------------|-----------------------------------|--|-------|------|------|-------|
| Symbol                 | Parameter                         | Test Conditions  | Value |      |      | Units |
|                        |                                   |  | Min.  | Typ. | Max. |       |
| V <sub>DSS</sub>       | Drain to Source Breakdown Voltage | V <sub>GS</sub> =0V, I <sub>D</sub> =- 250μA               | -60   | --   | --   | V     |
| I <sub>DSS</sub>       | Drain to Source Leakage Current   | V <sub>DS</sub> = -60V, V <sub>GS</sub> = 0V               | --    | --   | 1    | μA    |
| I <sub>GSS(F)</sub>    | Gate to Source Forward Leakage    | V <sub>GS</sub> = - 20V                                    | --    | --   | 100  | nA    |
| I <sub>GSS(R)</sub>    | Gate to Source Reverse Leakage    | V <sub>GS</sub> = + 20V                                    | --    | --   | -100 | nA    |
| V <sub>GS(TH)</sub>    | Gate Threshold Voltage            | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =- 250μA | -1.2  | -1.7 | -2.5 | V     |
| R <sub>DS(ON)</sub>    | Drain -to -Source On -Resistance  | V <sub>GS</sub> =- 10V, I <sub>D</sub> =- 20A              | --    | 8.5  | 11.0 | mΩ    |
| R <sub>DS(ON)</sub>    | Drain -to -Source On -Resistance  | V <sub>GS</sub> =- 4.5V, I <sub>D</sub> =- 20A             | --    | 10.5 | 13.0 | mΩ    |
| g <sub>FS</sub>        | Forward Transconductance          | V <sub>DS</sub> =- 10V, I <sub>D</sub> =- 20A              | 50    | --   | --   | S     |

| Dynamic Characteristics |                              |   |       |      |      |       |
|-------------------------|------------------------------|---|-------|------|------|-------|
| Symbol                  | Parameter                    | Test Conditions                           | Value |      |      | Units |
|                         |                              |   | Min.  | Typ. | Max. |       |
| C <sub>iSS</sub>        | Input Capacitance            | V <sub>GS</sub> =0V                       | --    | 3300 | --   | pF    |
| C <sub>oss</sub>        | Output Capacitance           | V <sub>DS</sub> =- 30V                    | --    | 700  | --   |       |
| C <sub>rSS</sub>        | Reverse Transfer Capacitance | f=1.0MHz                                  | --    | 19   | --   |       |
| R <sub>g</sub>          | Gate resistance              | V <sub>GS</sub> =0V, V <sub>DS</sub> Open | --    | 2.0  | --   | Ω     |

| Resistive Switching Characteristics |                      |   |       |      |      |       |
|-------------------------------------|----------------------|---|-------|------|------|-------|
| Symbol                              | Parameter            | Test Conditions                               | Value |      |      | Units |
|                                     |                      |   | Min.  | Typ. | Max. |       |
| t <sub>d(ON)</sub>                  | Turn -on Delay Time  | I <sub>D</sub> =- 20A, R <sub>L</sub> = 0.75Ω | --    | 4.5  | --   | ns    |
| t <sub>r</sub>                      | Rise Time            | V <sub>DS</sub> = -30V                        | --    | 2.5  | --   |       |
| t <sub>d(OFF)</sub>                 | Turn -Off Delay Time | V <sub>GS</sub> = -10V                        | --    | 14.5 | --   |       |
| t <sub>f</sub>                      | Fall Time            | R <sub>G</sub> = 3Ω                           | --    | 3.5  | --   |       |
| Q <sub>g</sub>                      | Total Gate Charge    | V <sub>GS</sub> =- 10V                        | --    | 47.5 | --   | nC    |
| Q <sub>gs</sub>                     | Gate Source Charge   | V <sub>DS</sub> =- 30V                        | --    | 14.0 | --   |       |
| Q <sub>gd</sub>                     | Gate Drain Charge    | I <sub>D</sub> =- 20A                         | --    | 7.6  | --   |       |

| Source-Drain Diode Characteristics |                         |   |       |      |      |       |
|------------------------------------|-------------------------|---|-------|------|------|-------|
| Symbol                             | Parameter               | Test Conditions   | Value |      |      | Units |
|                                    |                         |   | Min.  | Typ. | Max. |       |
| I <sub>S</sub>                     | Diode Forward Current   | T <sub>C</sub> =25 °C   | --    | --   | -80  | A     |
| I <sub>SM</sub>                    | Diode Pulse Current     |   | --    | --   | -320 | A     |
| V <sub>SD</sub>                    | Diode Forward Voltage   | I <sub>S</sub> =- 6.0A, V <sub>GS</sub> =0V                     | --    | --   | -1.2 | V     |
| t <sub>rr</sub>                    | Reverse Recovery time   | I <sub>S</sub> =- 20A, V <sub>DD</sub> =- 30V<br>dI/dt=100A/ μs | --    | 60   | --   | ns    |
| Q <sub>rr</sub>                    | Reverse Recovery Charge |   | --    | 105  | --   | nC    |

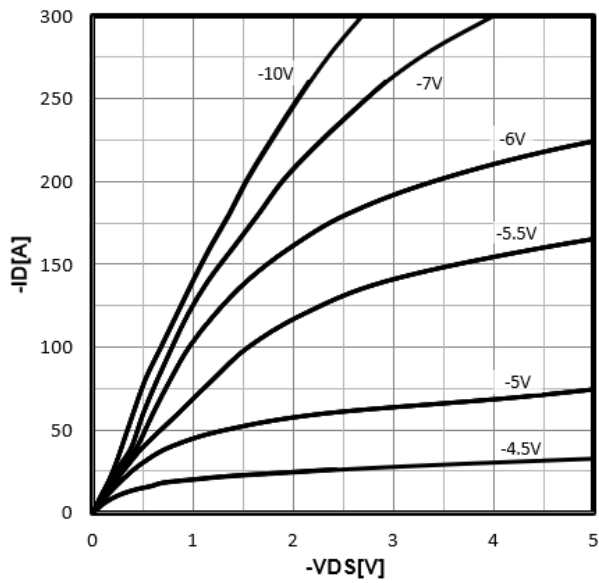
a1: Repetitive rating; pulse width limited by maximum junction temperature

a2: V<sub>DD</sub> =30V, L=0.3mH, R<sub>G</sub> =25Ω, Starting T<sub>j</sub>=25 °C

## Characteristics Curve:

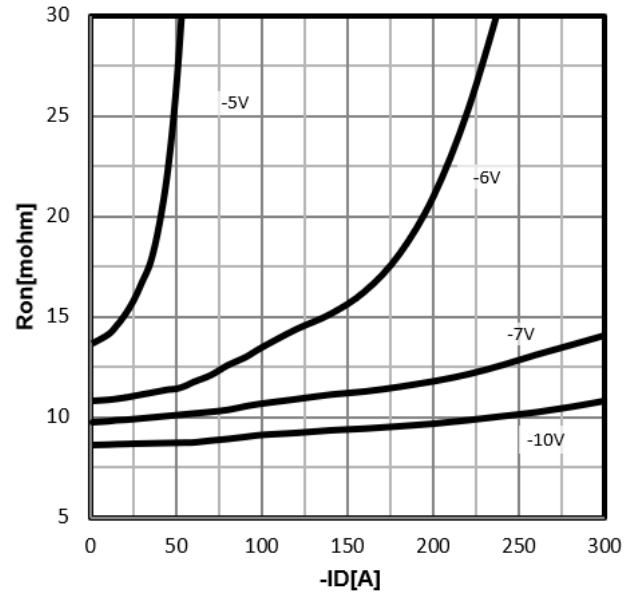
Typ. output characteristics

$$I_D = f(V_{DS})$$



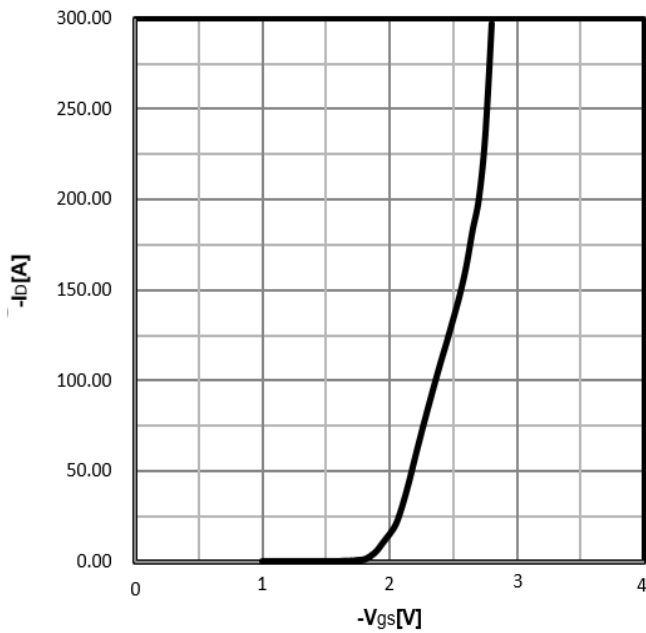
Typ. drain-source on resistance

$$R_{DS(on)} = f(I_D)$$



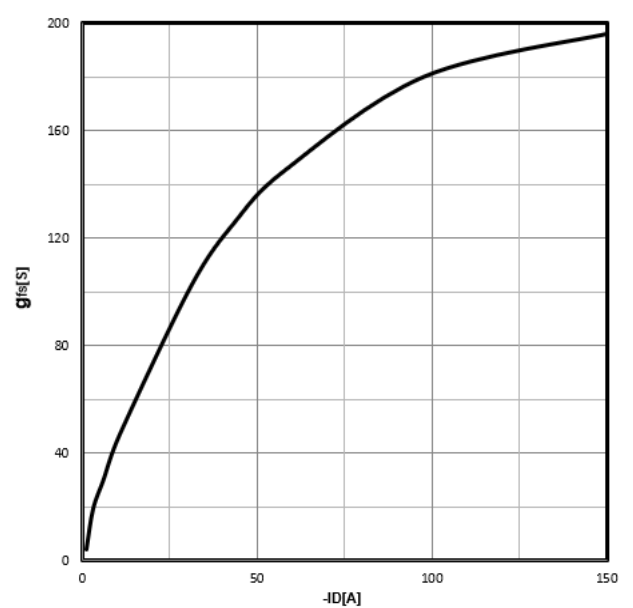
Typ. transfer characteristics

$$I_D = f(V_{GS})$$



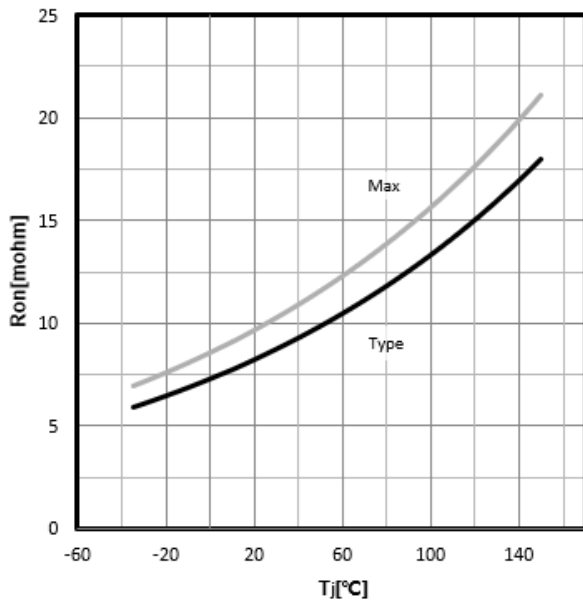
Typ. forward transconductance

$$g_{fs} = f(I_D)$$



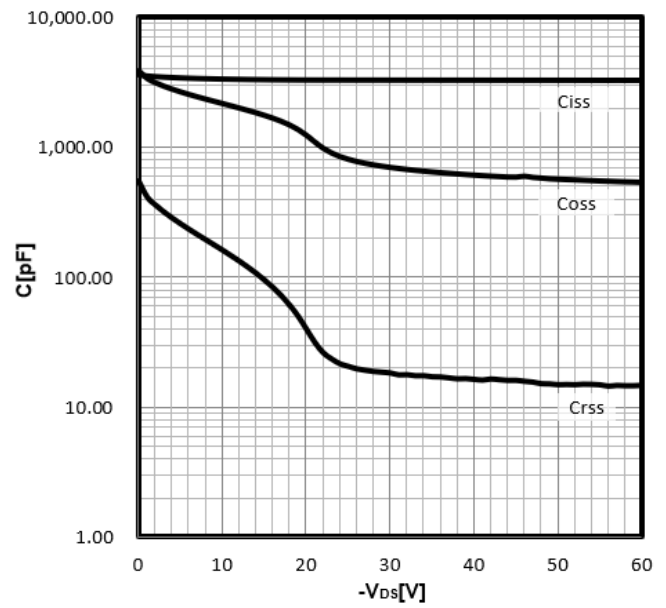
**Drain-source on-state resistance**

$R_{DS(on)} = f(T_j); I_D = -20A; V_{GS} = -10V$



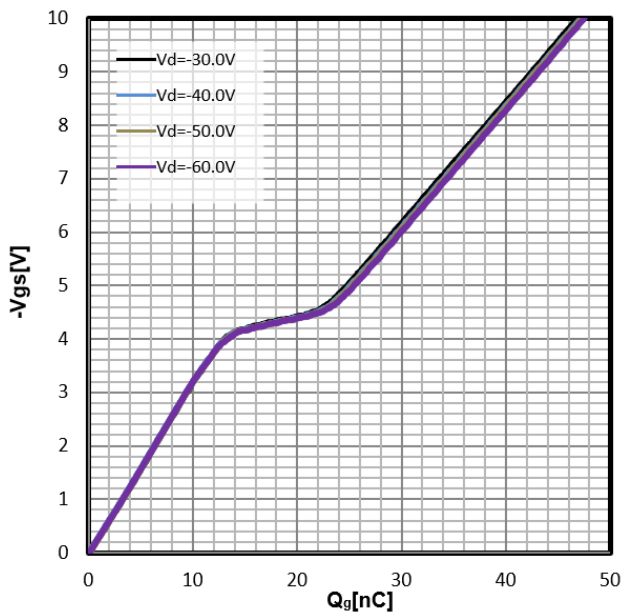
**Typ. capacitances**

$C = f(V_{DS}); V_{GS} = 0V; f = 1MHz$



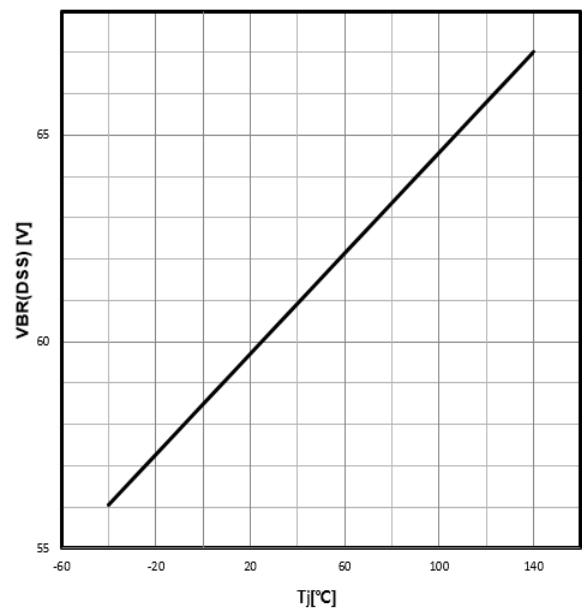
**Typ. gate charge**

$V_{GS} = f(Q_{gate}); I_D = -20A$

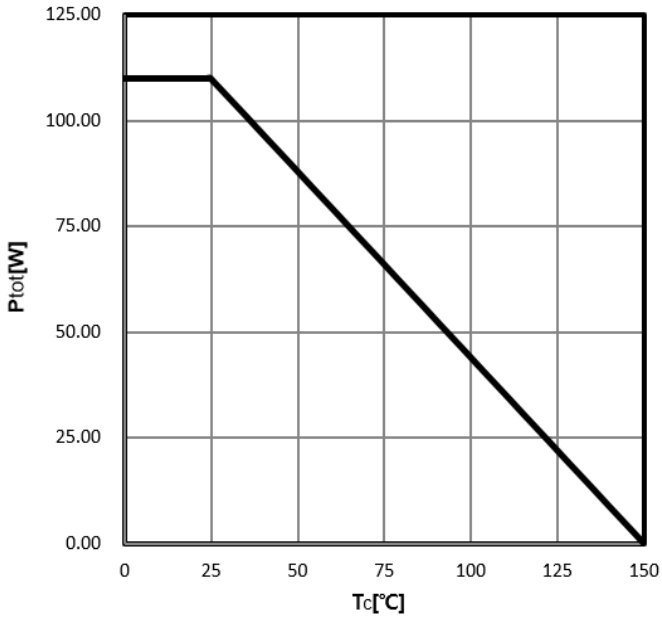


**Drain-source breakdown voltage**

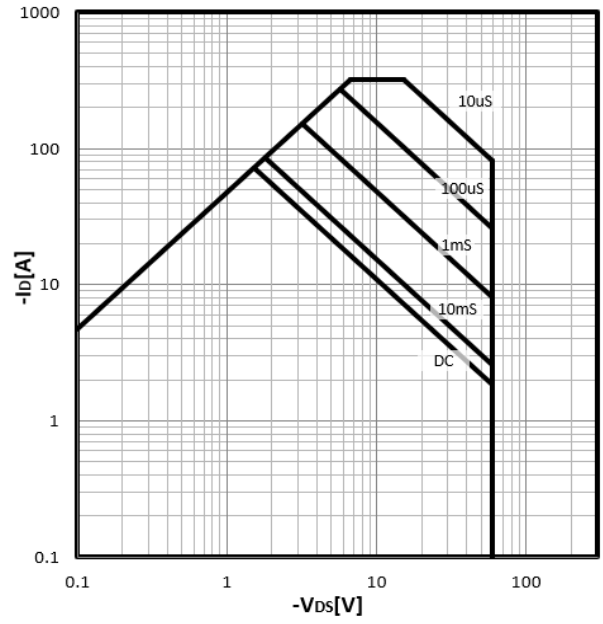
$V_{BR(DSS)} = f(T_j); I_D = -250uA$



**Power Dissipation**  
 $P_{tot}=f(T_c)$

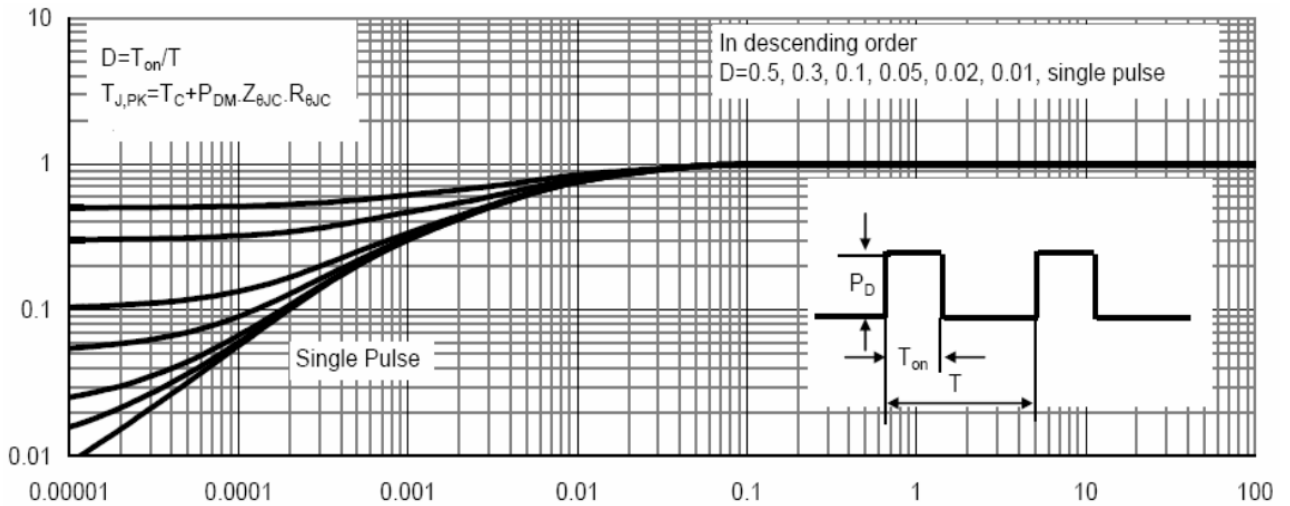


**Safe operating area**  
 $I_D=f(V_{DS})$

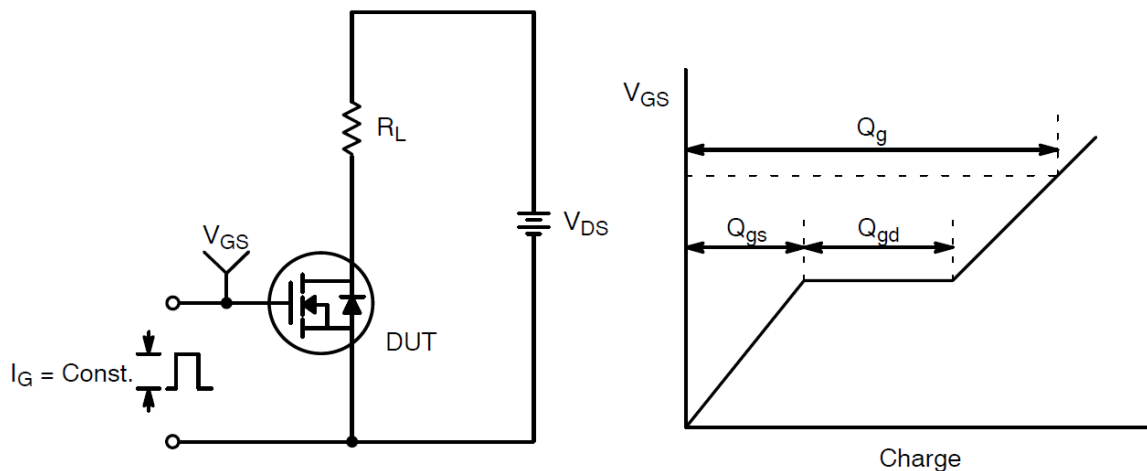


**Max. transient thermal impedance**

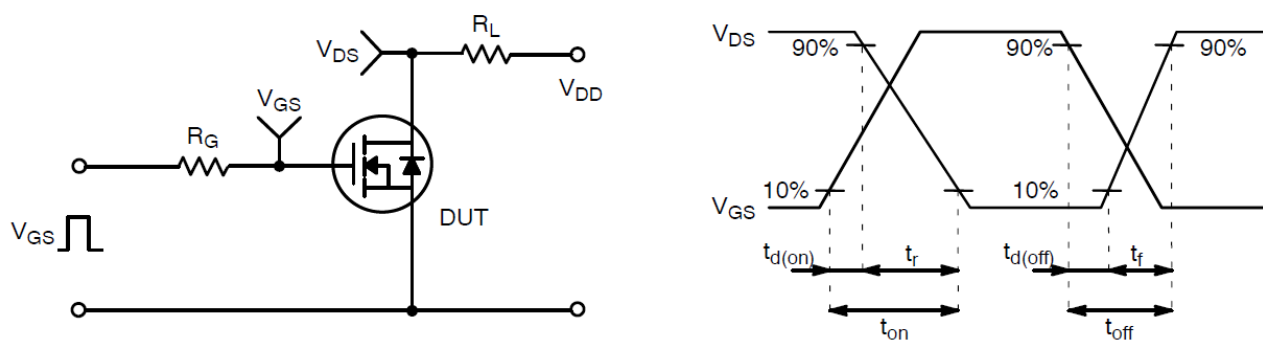
$$Z_{thJC}=f(t_p)$$



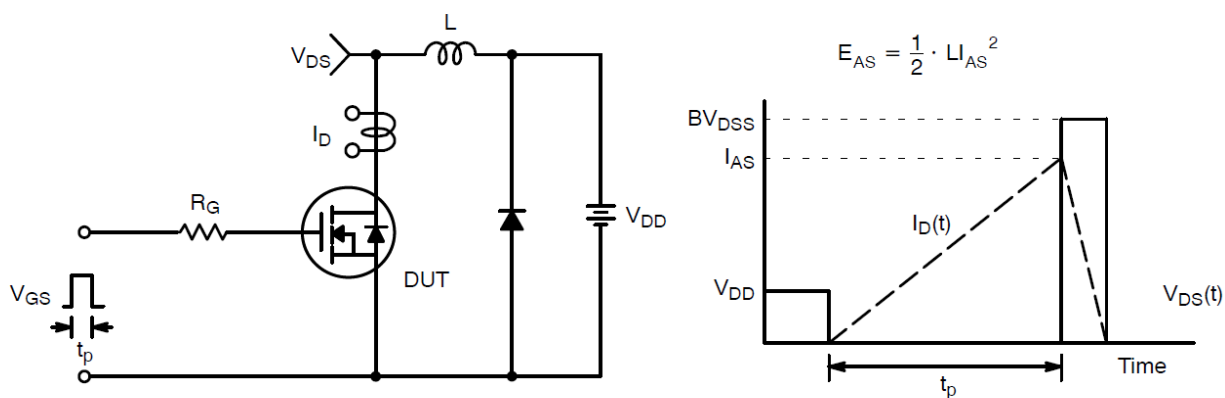
## Test Circuit and Waveform:



Gate Charge Test Circuit & Waveform

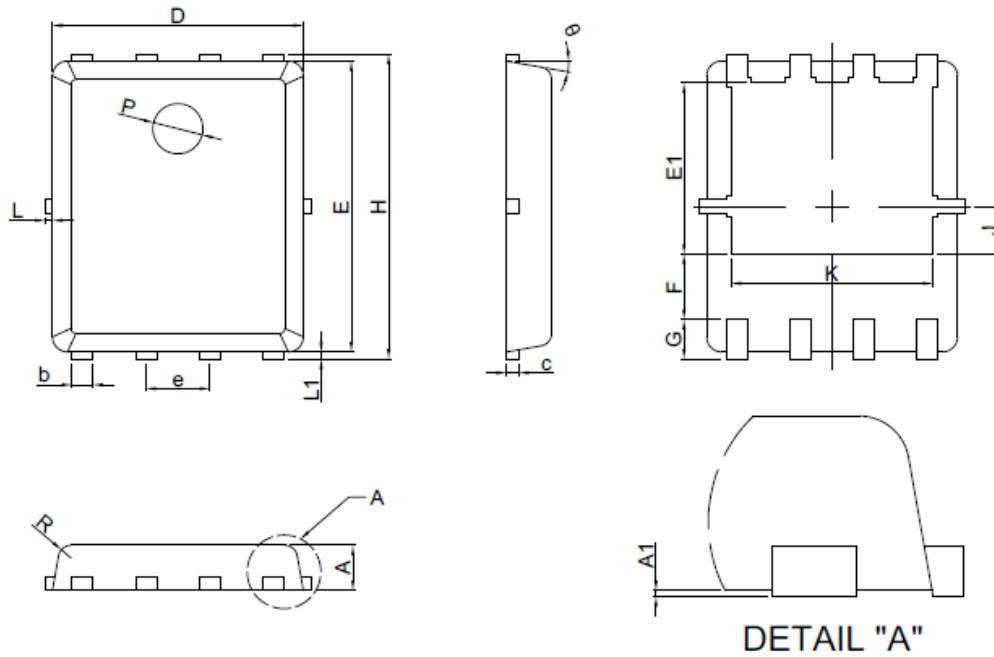


Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

## Package Information : PDFN5x6-8L



| Symbol | Dimensions In Millimeters |      |
|--------|---------------------------|------|
|        | MIN.                      | MAX. |
| A      | 0.80                      | 1.00 |
| A1     | 0.00                      | 0.05 |
| b      | 0.35                      | 0.49 |
| c      | 0.254REF                  |      |
| D      | 4.80                      | 5.20 |
| F      | 1.40REF                   |      |
| E      | 5.60                      | 5.90 |
| e      | 1.27BSC                   |      |
| H      | 5.80                      | 6.20 |
| L1     | 0.10                      | 0.18 |
| G      | 0.60REF                   |      |
| K      | 4.00REF                   |      |
| L      | -                         | 0.15 |
| J      | 0.95BSC                   |      |
| P      | 1.00REF                   |      |
| E1     | 3.40REF                   |      |
| θ      | 6°                        | 14°  |
| R      | 0.25REF                   |      |